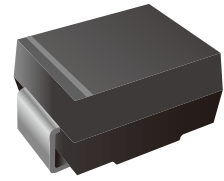


Surface Mount General Purpose Silicon Rectifiers

Features

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- Lead free in comply with EU RoHS 2011/65/EU directives



Mechanical Data

- Case: SMB
- Terminals: Solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end

Ordering Information

Part Number	Shipping	Reel
LTS3AB THRU LTS3MB-TR3	3000PCS Tape&Reel	13 inches

Maximum Ratings and Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	Symbol	LTS3AB	LTS3BB	LTS3DB	LTS3GB	LTS3JB	LTS3KB	LTS3MB	Unit
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current @ Fig.1	$I_{F(AV)}$	3							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	90							A
Maximum instantaneous forward voltage at 3.0A	V_F	1.1							V
Maximum DC reverse current at rated DC blocking voltage $T_A=25^\circ\text{C}$ $T_A=100^\circ\text{C}$	I_R	5 100							μA
Typical junction capacitance (NOTE 1)	C_J	28							pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$ $R_{\theta JC}$ $R_{\theta JL}$	43 9 18							$^\circ\text{C/W}$
Operating junction and storage temperature range	T_J, T_{STG}	-55 ~ +150							$^\circ\text{C}$

Note: (1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(2) P.C.B. mounted with 1.5" X 1.5" (3.81 cm X 3.81 cm) copper pad areas.



Characteristic Curves

Fig.1 Forward Current Derating Curve

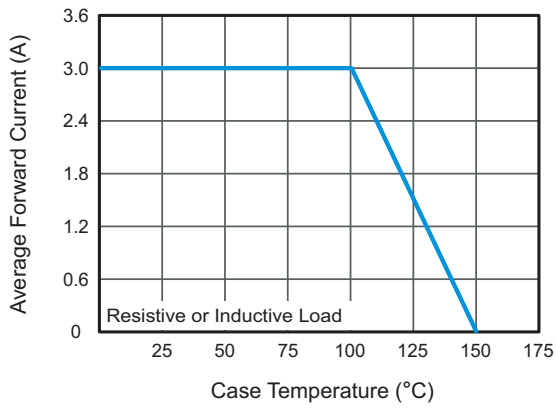


Fig.2 Typical Instantaneous Reverse Characteristics

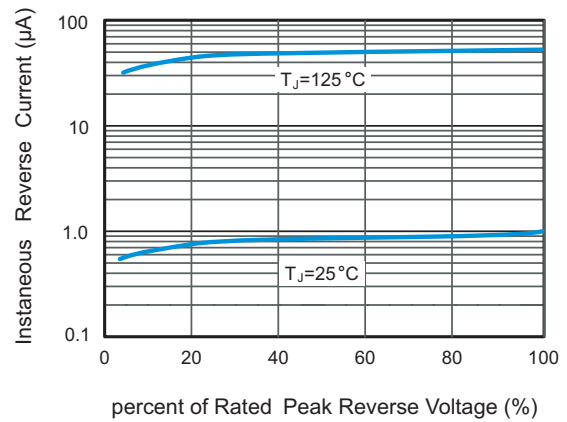


Fig.3 Typical Forward Characteristic

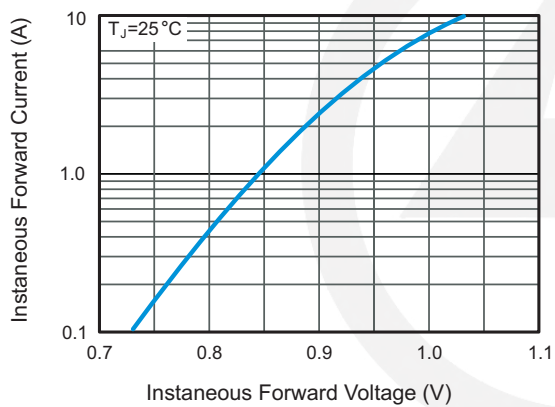


Fig.4 Typical Junction Capacitance

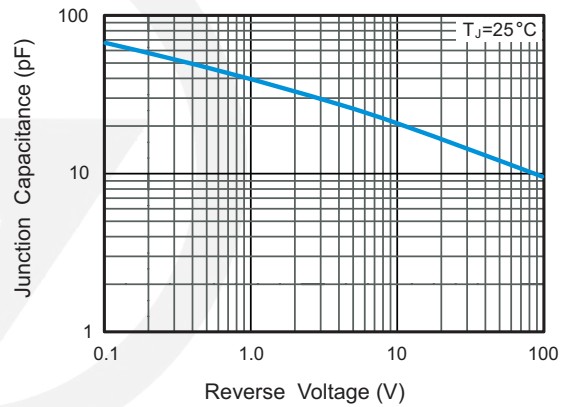
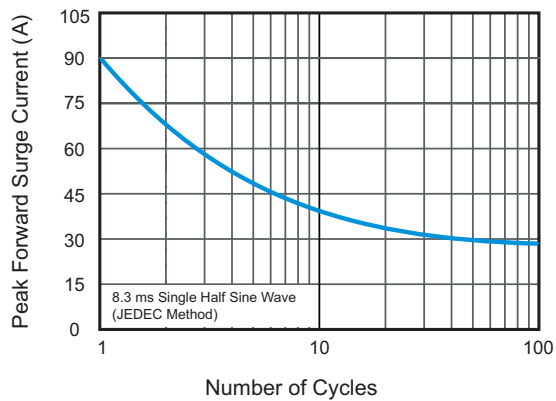
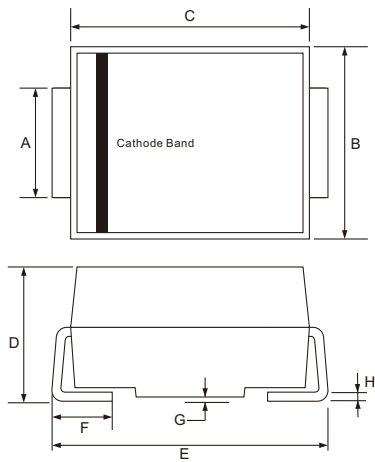


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



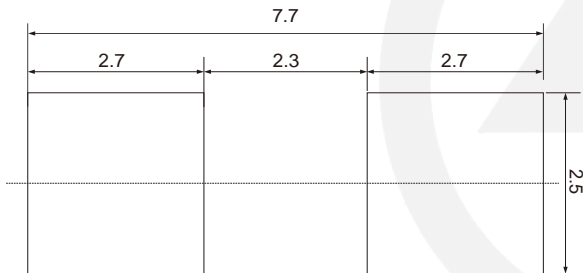
SMB Package Outline



Unit: mm

SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	1.90	2.20
B	3.30	3.94
C	4.05	4.75
D	2.13	2.65
E	5.08	5.59
F	0.76	1.52
G	0.203 TYP.	
H	0.15	0.31

SMB Suggested Pad Layout



Note:

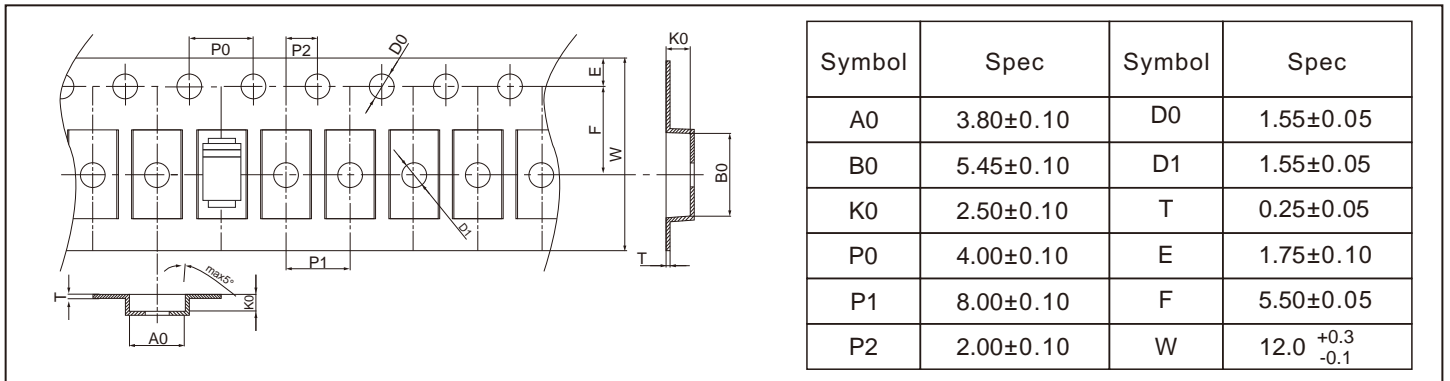
1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$
3. The pad layout is for reference purpose only.

Marking

Type number	Marking code
LTS3AB	S3A
LTS3BB	S3B
LTS3DB	S3D
LTS3GB	S3G
LTS3JB	S3J
LTS3KB	S3K
LTS3MB	S3M

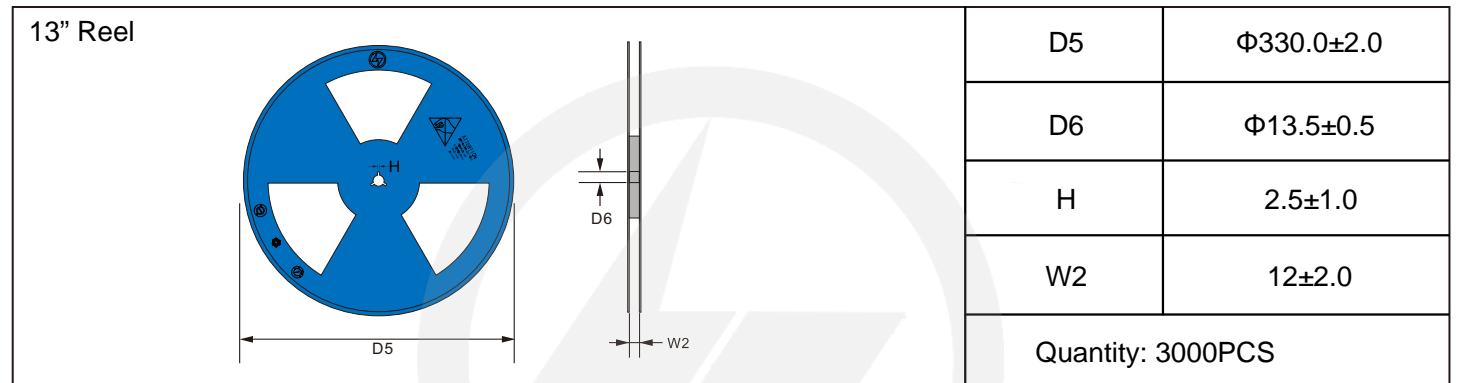
Carrier Tape Dimensions

Unit : mm

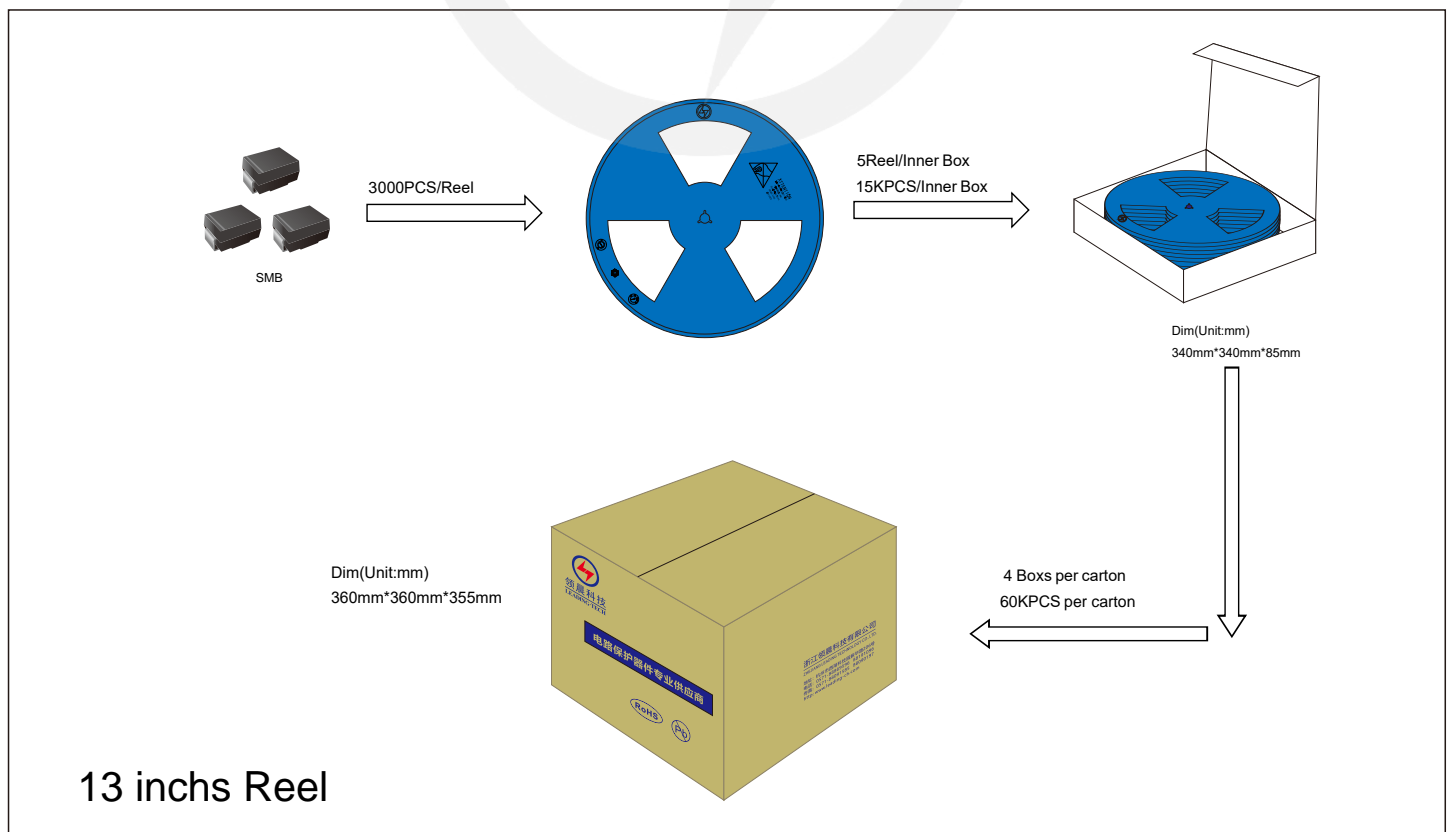


Reel Dimensions

Unit : mm



Packaging





Recommended Soldering Conditions



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3°C/second max.
Preheat	
-Temperature Min ($T_{S\ min}$)	150°C
-Temperature Max ($T_{S\ max}$)	200°C
-Time (min to max) (t_s)	60-180 seconds
$T_{S\ max}$ to T_L	
-Ramp-up Rate	3°C/second max.
Time maintained above:	
-Temperature (T_L)	217°C
-Time (t_L)	60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_p)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

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Version Update Information

Series NO.	Enactment/Revision Date	Effective Date	Version	Revision content	Revision Reason	Revision Person	Note
01	2024.5.18	2024.5.18	3.0	New File	/	Ding	
02	2025.06.16	2025.06.16	3.1	Update packaging information	/	Ding	